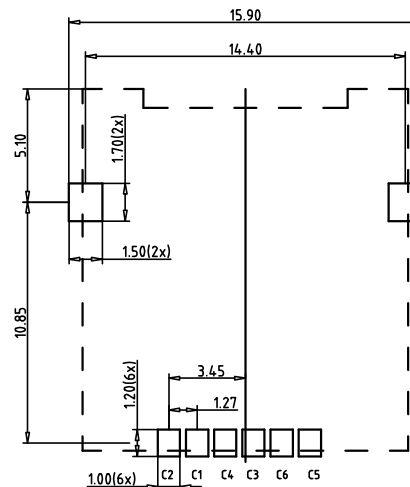
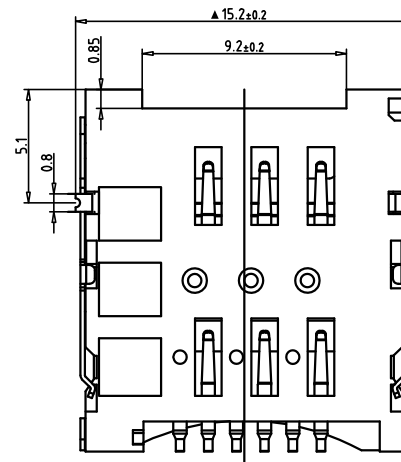
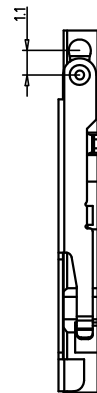
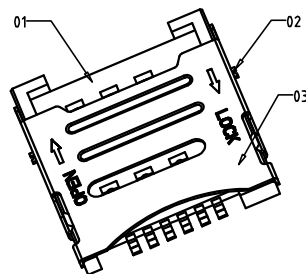
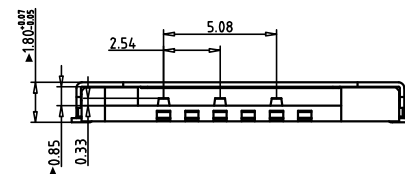
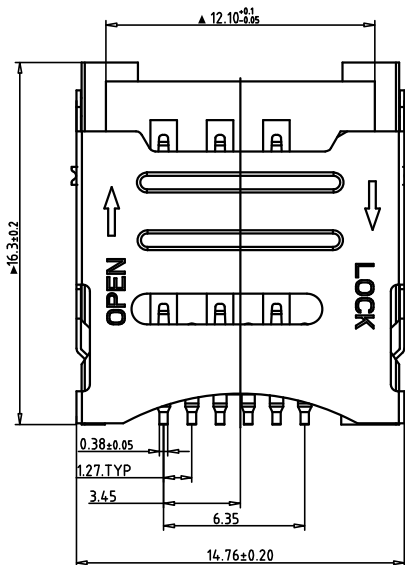
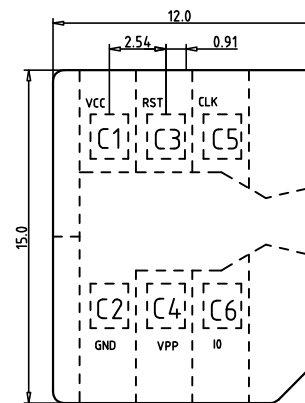


RoHS

REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A0		NEW RELEASE	07/12'16	YZZ		HAIYONG



PCB LAYOUT



MICRO SIM

一、材质和镀涂:

1、胶芯: LCP, UL 94 V - 0, 黑色

2、端子: 磷铜C5191-H, T=0.15, 镍底镀金

3、外壳: 不锈钢 SUS304 T=0.2

二、技术参数:

接触电阻: 100mΩ Max

绝缘阻抗: 1000MΩ Min(500DC)

额定电流: 每个接触件1A Max

额定电压: 30V Max(DC)

耐压: 500V r.m.s/min

使用温度: -40℃~85℃

湿度: 90%~95%

寿命: >3000次

PIN NO.	NAME	PIN NO.	NAME
C1	VCC	C4	VPP
C2	GND	C5	CLK
C3	RST	C6	IO

MILLIMETERS	INCH	UNITS MM	 东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.			
X° ± 2°	X° ± 2°	MAT'L				
.X ± 0.20	.XX ± 0.012	SEE NOTES				
.XX ± 0.10	.XXX ± 0.008	FINISH				
.XXX ± 0.05	.XXXX ± 0.008	SEE NOTES				
			PART NUMBER: XB-402013062	TITLE: Micro Sim卡 1.8H掀盖式		
			APPD: HAIYONG	DWG NO.: C-402013062-00		
			CHKD: --			
			DR: YZZ			
				SCALE 1:1	SHEET 1/2	REV. A0